



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

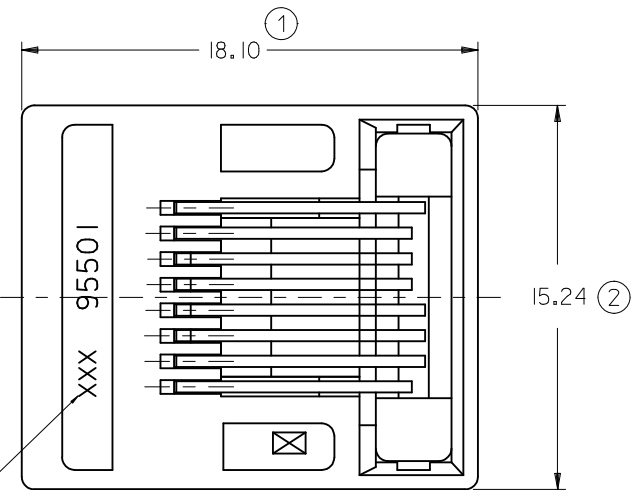
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



NOTES:

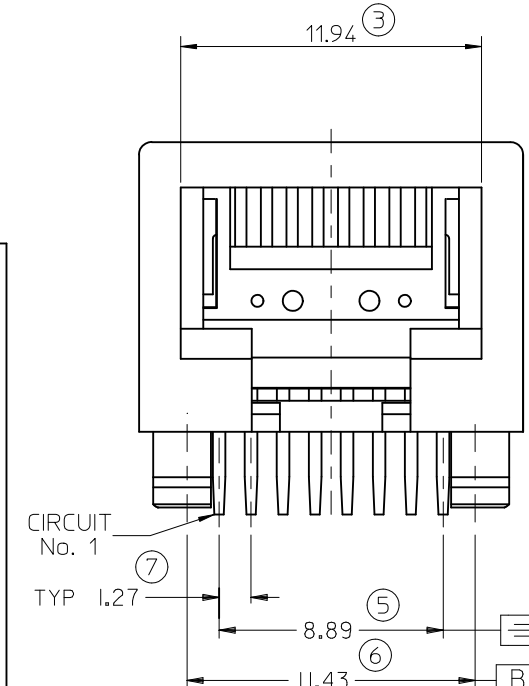
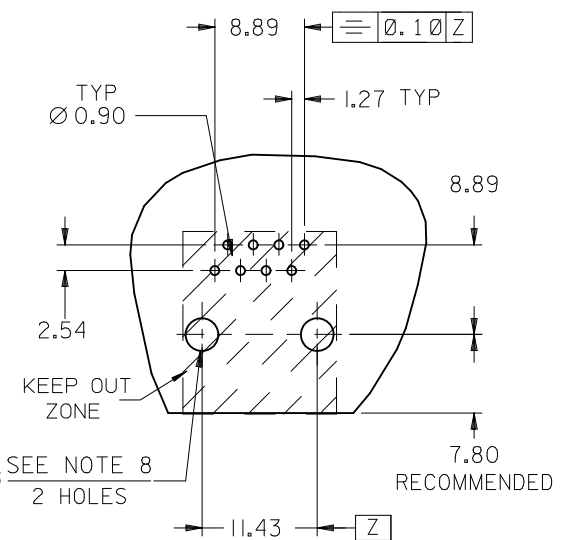
- 1- MATERIAL:
 -HOUSING: LCP FIBER GLASS FILLED UL 94-V0, COLOR BLACK.
 -TERMINAL: PHOSPHOR BRONZE.
 BASE FINISH: NICKEL
 CONTACT SURFACE FINISH:
 GOLD
 OR
 GOLD FLASH OVER PALLADIUM NICKEL.
 EXCEEDS PRODUCT REQUIREMENTS BASED ON PS-85503-001
- 2- JACK FOR MATING WITH F.C.C.68 PLUGS (90075 MOLEX SERIES).
 3- PRODUCT SPECIFICATION PS-85503-001
 4- APPLICATION SPECIFICATION AS-85513-001
 5- PACKAGING SPECIFICATION PK-95001: STANDARD PACKAGING SHEET I.
 6- EXCEEDS CATEGORY 5E PERFORMANCE.
 7- PC BOARD THICKNESS: 1.57
 8- CONVECTION SOLDERING DIA 3.25±0.05,
 WAVE SOLDERING DIA 3.2±0.1
 9- MANUFACTURING I.D. CAN BE MXF, MG OR MXI.
 LAST INSPECTION NUMBER: 14

MATERIAL No. 85503-5001

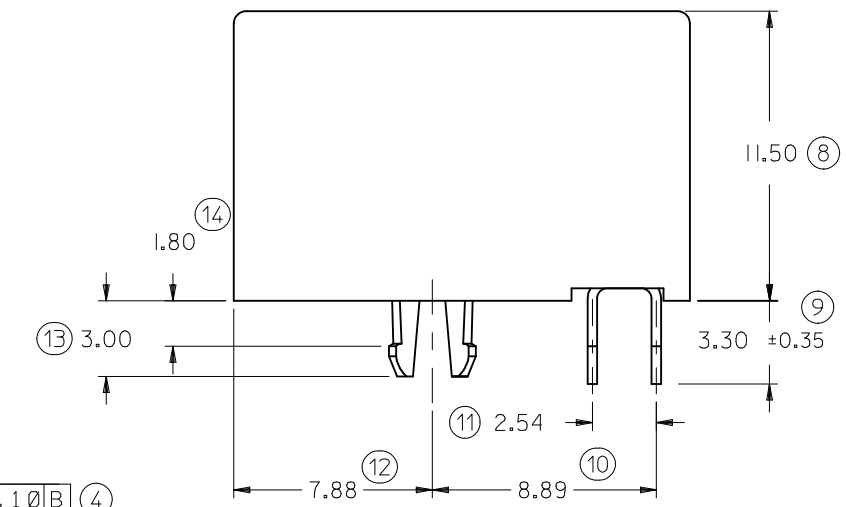


NOTE 9

P.C.B. MOUNTING PATTERNS
 (SEE FROM COMPONENT SIDE)
 SCALE 2:1



CIRCUIT No. 1
 TYP 1.27



REMOVED PART MODIFIED NOTES EC NO: IPG2012-0604 DRW:DBY/RES 2012/03/30 CHKD:SMC/REVY 2012/04/02 APPR:EFOLAN 2012/06/26	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▽=0 ∇=0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.15 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 1/2°	MM ONLY	5:1	METRIC	☉ □ THIRD ANGLE PROJECTION	
	DRAWN BY: DBY/RES CHECKED BY: SMC/REVY APPROVED BY: EFOLAN	DATE: 2012/03/30 DATE: 2012/04/02 DATE: 2012/06/26	DRAWN BY: TMARTIN CHECKED BY: FCARABETTA APPROVED BY: KNOLLER	DATE: 2005/03/08 DATE: 2005/03/08 DATE: 2005/03/08	TITLE HIGH SPEED MODULAR JACK RIGHT ANGLE LOW PROFILE THROUGH HOLE 8 CIRCUIT		
	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-85503-101	MOLEX INCORPORATED SHEET NO. 1 OF 1				

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION